

# Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions	
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	500			V	$V_{GS} = 0V, I_{D} = 1.0mA$	
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.78		V/°C	Reference to 25°C, I <sub>D</sub> = 1.0mA	
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			0.4	Ω	V <sub>GS</sub> = 10V, I <sub>D2</sub> = 7.75A ④	
				0.5		V <sub>GS</sub> = 10V, I <sub>D1</sub> = 12A ④	
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Gfs	Forward Transconductance	5.5			S	$V_{DS} = 15V, I_{D2} = 7.75A$ @	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current			25		$V_{DS} = 400V, V_{GS} = 0V$	
				250	μA	$V_{DS} = 400V, V_{GS} = 0V, T_{J} = 125^{\circ}C$	
$I_{GSS}$	Gate-to-Source Leakage Forward			100	nA	V <sub>GS</sub> = 20V	
	Gate-to-Source Leakage Reverse			-100	шА	V <sub>GS</sub> = -20V	
$Q_G$	Total Gate Charge	55		120		I <sub>D1</sub> = 12A	
$Q_{GS}$	Gate-to-Source Charge	5.0		19	nC	V <sub>DS</sub> = 250V	
$Q_{GD}$	Gate-to-Drain ('Miller') Charge	27		70		V <sub>GS</sub> = 10V	
t <sub>d(on)</sub>	Turn-On Delay Time			35		V <sub>DD</sub> = 250V	
tr	Rise Time			190	20	$I_{D1} = 12A$	
t <sub>d(off)</sub>	Turn-Off Delay Time			170	ns	$R_G = 2.35\Omega$	
t <sub>f</sub>	Fall Time			130		V <sub>GS</sub> = 10V	
Ls +L <sub>D</sub>	Total Inductance		6.1			Measured from Drain lead (6mm / 0.25 in from package) to Source lead (6mm/ 0.25 in from package)	
C <sub>iss</sub>	Input Capacitance		2700			V <sub>GS</sub> = 0V	
Coss	Output Capacitance		600		pF	V <sub>DS</sub> = 25V	
C <sub>rss</sub>	Reverse Transfer Capacitance		240			f = 1.0MHz	

# **Source-Drain Diode Ratings and Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Is	Continuous Source Current (Body Diode)			12	۸	
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①			48	Α	
$V_{SD}$	Diode Forward Voltage			1.7	V	$T_J = 25^{\circ}C, I_S = 12A, V_{GS} = 0V$
t <sub>rr</sub>	Reverse Recovery Time			1600	ns	$T_J = 25^{\circ}C, I_F = 12A, V_{DD} \le 30V$
$Q_{rr}$	Reverse Recovery Charge			14	μC	di/dt = 100A/μs ④
t <sub>on</sub>	Forward Turn-On Time	Intrins	ic turn-c	n time i	s negligib	le (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )

# **Thermal Resistance**

	Symbol	Parameter	Min.	Тур.	Max.	Units	
$R_{\theta}$	JC	Junction-to-Case			0.83	°C/W	
$R_{\theta}$	)JA	Junction-to-Ambient (Typical socket mount)			30	- C/vv	

#### Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- $^{\circ}$  V<sub>DD</sub> = 50V, starting T<sub>J</sub> = 25°C, L= 0.111mH, Peak I<sub>L</sub> = 12A, V<sub>GS</sub> = 10V.
- $\ \ \,$   $\ \ \,$   $\ \ \,$   $I_{SD} \ \le \ 12A,$  di/dt  $\ \ \,$   $\ \ \,$   $130A/\mu s,$   $V_{DD} \ \le \ 500V,$   $T_{J} \ \le \ 150^{\circ}C.$  Suggested  $R_{G}$  =2.35  $\Omega$

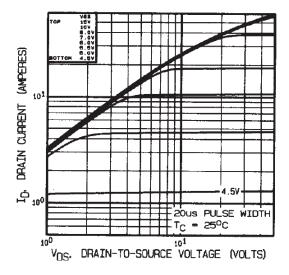


Fig 1. Typical Output Characteristics

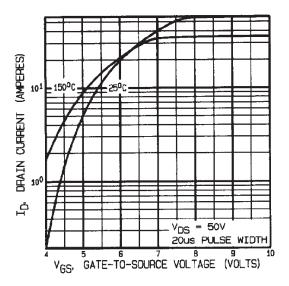


Fig 3. Typical Transfer Characteristics

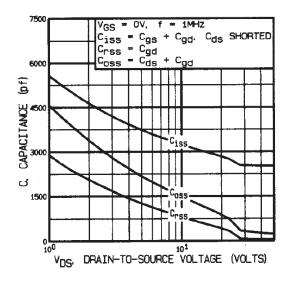


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

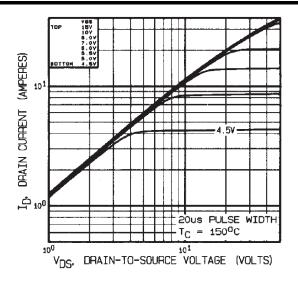


Fig 2. Typical Output Characteristics

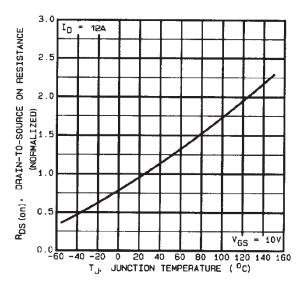


Fig 4. Normalized On-Resistance Vs. Temperature

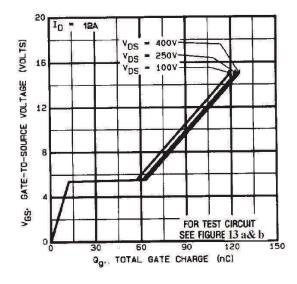


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

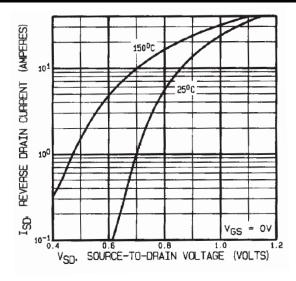


Fig 7. Typical Source-Drain Diode Forward Voltage

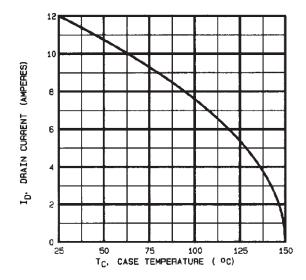


Fig 9. Maximum Drain Current Vs. Case Temperature

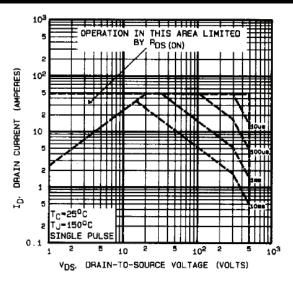
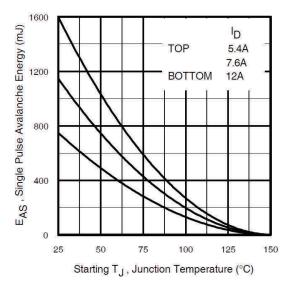


Fig 8. Maximum Safe Operating Area



**Fig 10.** Maximum Avalanche Energy Vs. Drain Current

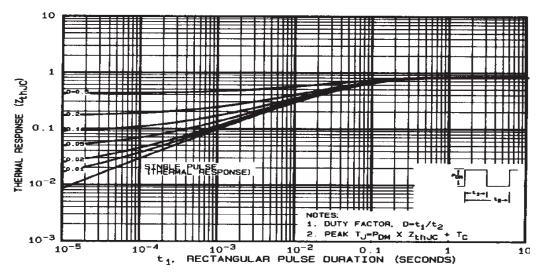


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

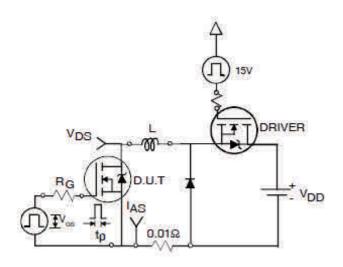


Fig 12a. Unclamped Inductive Test Circuit

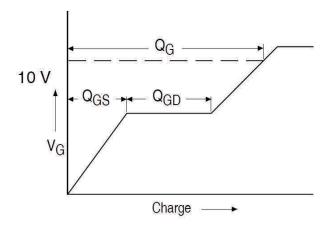


Fig 13a. Gate Charge Waveform

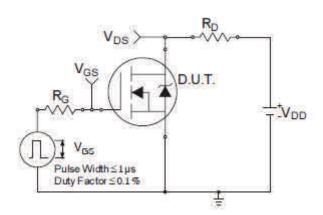


Fig 14a. Switching Time Test Circuit

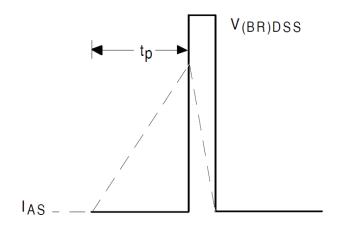


Fig 12b. Unclamped Inductive Waveforms

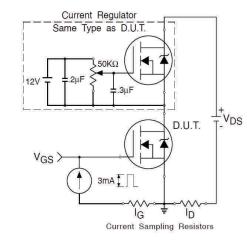


Fig 13b. Gate Charge Test Circuit

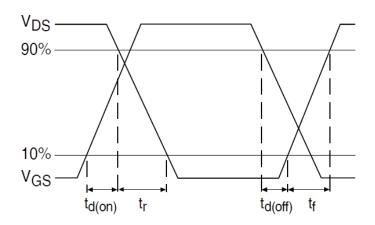
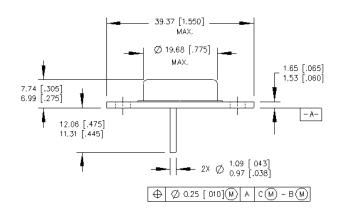
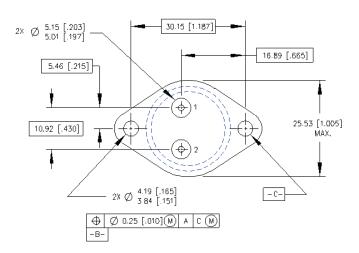


Fig 14b. Switching Time Waveforms



## Case Outline and Dimensions - TO-204AA (Modified TO-3)





#### PIN ASSIGNMENTS

**HEXFET SCHOTTKY** <u>IGBT</u> 1 - SOURCE 1 - ANODE 1 1 - GATE 2 - GATE 3 - DRAIN (CASE) 2 - EMITTER 3 - COLLECTOR (CASE) 2 - ANODE 2

3 - COMMON CATHOD (CASE)

#### NOTES:

- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS ARE SHOWN IN MILIMETERS [ INCHES]
  4. OUTLINE CONFORMS TO JEDEC OUTLINE TO -204-AA



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